



Substrate: $0.79mm \pm 0.18mm [0.031" \pm 0.007"]$ FR4/G10 or equivalent high temp material. 17µm [1/2 oz.] Cu clad. SnPb plating.



Substrate: 1.59mm ± 0.18 mm $[0.062" \pm 0.007"]$ FR4/G10 or equivalent high temp material. Non-clad.



Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.). Contact material- BeCu; finish 0.25µm $[10\mu'']$ Au over $2.54\mu m$ $[100\mu'']$ Ni (min.).

<u>Description:</u> 64 postiom MLF surface mount foot

64 position (+1 Gnd index pin), 1.0mm pitch UGA female receptacles (top) to 64 position, 0.5mm MLF pattern.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-MLF64A-A-02 Drawing	Status: Released	Scale	6:1	Rev: A
© 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 8/5/04	
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